

Product / Process Change Notification



N° 2015-084-B !! UPDATE !!

- Updated Information marked in **BLUE TYPE**
- Original PCN N° 2015-084-A dated 2016-08-08

Dear Customer,

Attached please find an updated PCN 2015-084-B for your attention.

Updates covered by B version:

- Title adapted
- Reason of change modified
- Wafer Fab Location Change: Infineon Technologies, Regensburg removed
- Wire Bond Change: wire bond material ,Gold' removed
- Glue Change: die attach material ,EN4900 GC' removed
- Wafer Test Location Change: Infineon Technologies, Villach as additional wafer fab and test location removed
- Traceability corrected
- New SP-No added
- Package Marking added
- Data Sheet Update Rev 1.7 added

Introduction of copper wire bond and ~~additional~~ Infineon Kulim, Malaysia as wafer fab and wafer test location affecting TLE7240SL

If you have any questions, please do not hesitate to contact your local Sales office.

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■ Original PCN N° 2015-084-A dated 2016-08-08

► **Products affected:**

Sales Name	SP N°	OPN	Package
TLE7240SL	SP000897440	TLE7240SLXUMA1	PG-SSOP-24

► **Detailed Change Information:**

Subject: Introduction of copper wire bond and [additional Infineon Kulim, Malaysia](#) ~~as~~ wafer fab and wafer test location affecting TLE7240SL

Reason: Copper (Cu) wire bonding is part of Infineon's continuous drive to deliver higher performance products. A copper wire enables superior electrical, thermal and reliability performance compared to [Gold \(Au\)](#), making it an excellent interconnect solution for automotive packaging.

~~Expansion~~ [Transfer](#) of wafer production and wafer test capacity. Due to continuously raising demand for Infineon automotive products we have to implement the well-known front end (FE) location Kulim as [an additional](#) wafer fab and wafer test location.

Description:

	<u>Old</u>	<u>New</u>
Wafer fab location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia ☞ Infineon Technologies AG, Regensburg, Germany
Wafer test location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Villach, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia ☞ Infineon Technologies AG, Villach, Germany
Wire bond	<ul style="list-style-type: none"> ■ Gold 30 µm 	<ul style="list-style-type: none"> ■ Copper 30 µm ☞ Gold 30 µm
Glue	<ul style="list-style-type: none"> ■ EN4900 GC 	<ul style="list-style-type: none"> ■ A3230 ☞ EN4900 GC
SP N°	<ul style="list-style-type: none"> ■ SP000897440 	<ul style="list-style-type: none"> ■ SP001644078
Package Marking	<ul style="list-style-type: none"> ■ TLE2740SL Date Code RU lot # 	<ul style="list-style-type: none"> ■ TLE2740SL Cu Date Code 1E lot #
DS Update	<ul style="list-style-type: none"> ■ DS Rev 1.6 	<ul style="list-style-type: none"> ■ DS Rev 1.7

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▶ **Product Identification:**

Traceability assured via lot number [internal Bau-numbers](#).
[No change in SP ordering number](#). and new SP number.

▶ **Impact of Change:**

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No impact on fit and form.

▶ **Attachments:**

[4_cip15084B DS Update Rev 1.7](#)

▶ **Time Schedule:**

- Final qualification report:
- First samples available:
- Intended start of delivery:

	2015-084-A	2015-084-B
	available	available
	available	on request
	01-March-2017	01-April-2018 or earlier after customer request

If you have any questions, please do not hesitate to contact your local Sales office.